

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A copper-based alloy containing comprising 5.0 to 10.0 wt% of Zn, at least 2.8 to 5.0 wt% of Sn, 0.4 to 3.0 wt% of Bi, and satisfying $0 < \text{Se} \leq 0.35$ wt% to enable securing prescribed machinability and wholesome ness of a casting and exalt mechanical properties thereof, and a balance of Cu and unavoidable impurities.
2. (Currently amended) A The copper-based alloy according to claim 1, wherein it contains the Se of comprising 0.2 wt% or less of Se.
3. (Currently amended) A The copper-based alloy according to claim 1, wherein it contains the Sn in a range of comprising 3.5 to 4.5 wt% of Sn.
4. (Currently amended) A The copper-based alloy according to claim 1, wherein it further satisfies comprising $0 < \text{P} < 0.5$ wt%.
5. (Currently amended) A The copper-based alloy according to claim 1, wherein it further contains comprising Ni of 3.0 wt% or less of Ni.
6. (Currently amended) A copper-based alloy containing comprising at least Sn, Bi and Se and containing at least one non-solid solution substance formed of an alternative component for Pb in an amount of 1.0 vol% or more to enable suppression of occurrence of a casting defect, 5.0 to 10.0 wt% of Zn, 2.8 to 5.0 wt% of Sn, 0.4 to 3.0 wt% of Bi, $0 < \text{Se} \leq 0.35$ wt%, and a balance of Cu and unavoidable impurities, and further comprising 1.20 to 4.90 vol% of at least one selected from the group consisting of a non-solid solution substance secured with Bi and a non-solid solution substance secured with Bi and Se.
7. (Currently amended) A The copper-based alloy according to claim 6, wherein it contains comprising the at least one non-solid solution substance secured with Bi.

8. (Currently amended) A-The copper-based alloy according to claim 6, wherein it contains comprising the at least one non-solid solution substance secured with Bi and Se.

9. (Cancelled)

10. (Previously presented) A cast ingot produced using the alloy according to claim 1 and a liquid-contacting part formed of the cast ingot.

11. (Currently amended) A-The copper-based alloy according to claim 2, wherein it contains the Sn in a range of comprising 3.5 to 4.5 wt% of Sn.

12. (Currently amended) A-The copper-based alloy according to claim 2, wherein it further satisfies comprising $0 < P < 0.5$ wt%.

13. (Currently amended) A-The copper-based alloy according to claim 3, wherein it further satisfies comprising $0 < P < 0.5$ wt%.

14. (Currently amended) A-The copper-based alloy according to claim 2, wherein it further contains comprising Ni of 3.0 wt% or less of Ni.

15. (Currently amended) A-The copper-based alloy according to claim 3, wherein it further contains comprising Ni of 3.0 wt% or less of Ni.

16. (Currently amended) A-The copper-based alloy according to claim 4, wherein it further contains comprising Ni of 3.0 wt% or less of Ni.

17-18. (Cancelled)

19. (Previously presented) A cast ingot produced using the alloy according to claim 2 and a liquid-contacting part formed of the cast ingot.

20. (Previously presented) A cast ingot produced using the alloy according to claim 3 and a liquid-contacting part formed of the cast ingot.

21. (Previously presented) A cast ingot produced using the alloy according to claim 4 and a liquid-contacting part formed of the cast ingot.

22. (Previously presented) A cast ingot produced using the alloy according to claim 5 and a liquid-contacting part formed of the cast ingot.

23. (Previously presented) A cast ingot produced using the alloy according to claim 6 and a liquid-contacting part formed of the cast ingot.

24. (Previously presented) A cast ingot produced using the alloy according to claim 7 and a liquid-contacting part formed of the cast ingot.

25. (Previously presented) A cast ingot produced using the alloy according to claim 8 and a liquid-contacting part formed of the cast ingot.

26. (Cancelled)